

Exhibit D



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October 20, 2006

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VIA FEDERAL EXPRESS

Howard G. Pollack
Fish & Richardson P.C.
500 Arguello Street, Suite 500
Redwood City, CA 94036

Re: Power Integrations v. Fairchild Semiconductor et al. (CA 04-1371 JJF)

Dear Howard:

Following up on my letter of earlier this week, please find the enclosed CDs. The CD that is Bates labeled I-000411 contains a bond diagram of Mr. Beasom's prototype wafers. The CD that is Bates labeled I-000412-414 contains photographs of the prototype wafers and packaged test-chips. We hope to obtain additional documents from Intersil. We will, of course, produce them to Power Integrations as soon as we receive them.

Sincerely,

Brian H. VanderZanden

BHV:ma5

cc: William J. Marsden, Jr.
Frank E. Scherkenbach

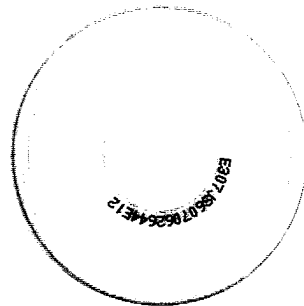
Power Integrations v. Fairchild
Case no. 04-1371 JJF



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Third Party Production
Intersil
I-000412 - I-000414
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Power Integrations v. Fairchild
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I-000411
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